

Mailed: August 27, 2003
Filing Due Date: October 27, 2003

NOTICE OF GROUND OF REJECTION

Applicant : Mitsubishi Denki Kabushiki Kaisha
Attorney : First Law Offices of Korea
Pat. Appln. No. : 10-2001-0058570
Title of the Invention : Semiconductor Device and Manufacturing Method of the Same

This is to notice, under the provision of Article 63 of the Patent Law, that the grounds for rejection as specified below are found as a result of examination of the present application. If the applicant has any argument or wishes to make amendments, please file a response or an amendment by October 27, 2003. (The due date is extensible one month at a time. Any notification acknowledging such extension will not be issued.)

Grounds

The invention as specified by the claims 1 and 2 of the present application could have been readily made by a person skilled in the art before the filing of the present application from the references specified below. Accordingly, a patent cannot be granted thereto under the provision of Paragraph 2 of Article 29 of the Patent Law.

Remarks

Claims 1-2 of the present application is directed to a semiconductor device and a method of manufacturing the same, wherein a surface of an active region of a semiconductor substrate is entirely rounded so as to be inclined downward toward an isolation region of a bird's beak. Impurities are implanted into the active region through a first insulating film and a bird's beak portion, and after the first insulating film is removed, a gate electrode is formed with a second insulating film interposed. The invention in Cited Reference 1 (Korean Patent Laying-Open No. 1993-9059) discloses a method of forming a semiconductor device including an active region having a rounded surface and being inclined toward an element-isolating film (Fig. 2). The invention in Cited Reference 2 (Japanese Patent Laying-Open No. 2000-200878) discloses a method of manufacturing a semiconductor device, including implanting an impurity for threshold voltage onto an insulating

film on an activ region that is entirely rounded over a sharp portion of a surface of a semiconductor substrate, followed by a subsequent step (Figs. 16-25). The present invention could easily have been made by those having ordinal skills in the art in view of the inventions in Cited References 1 and 2.

[Appended Documents]

Reference 1 Korean Patent Laying-Open No. 1993-9059

Reference 2 Japanese Patent Laying-Open No. 2000-200878

JSL

Docket N .: 57454-162

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Customer Number: 20277
Yukio MAKI : Confirmation Number: 2289
 Serial No.: 09/909,975 : Group Art Unit: 2811
 Filed: July 23, 2001 : Allowed: October 22, 2003
 Examiner: S. Gebremariam

For: SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD OF THE SAME

REQUEST FOR ACKNOWLEDGEMENT OF THE CITED ART

Mail Stop ISSUE FEE
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

Match and Return

Sir:

We are in receipt of the Notice of Allowance dated October 22, 2003.

In reviewing the file, it is noted that we have not received acknowledgement of the Information Disclosure Statement and cited art filed November 24, 2003. Enclosed are copies of the Information Disclosure Statement, PTO-1449 and stamped return postcard acknowledgement.

Applicant hereby respectfully requests that:
 the appropriately acknowledged PTO-1449 be furnished to Applicant; and
 the record be clarified to confirm that the cited art has been considered and made of record.

Respectfully submitted,

MCDERMOTT WILL & EMERY


 Stephen A. Becker
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 Date: December 12, 2003

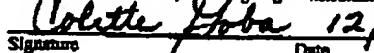
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Number of Pages, Including Cover: Six

Re: U.S. Application No. 09/909,975

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Docket No.: 57454-162

PATENT**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of

Customer Number: 20277

Yukio MAKI

Confirmation Number:

Serial No.: 09/909,975

Group Art Unit: 2811

Filed: July 23, 2001

Examiner: S. Gebremariam

For: SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD OF THE SAME

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INFORMATION DISCLOSURE STATEMENT

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This Information Disclosure Statement is being filed more than three months after the U.S. filing date and after the mailing date of a Final Rejection or Notice of Allowance, but before payment of the Issue Fee.

REQUEST TO CONSIDER REFERENCES AFTER CLOSE OF PROSECUTION AND**BEFORE PAYMENT OF ISSUE FEE**

The undersigned hereby requests consideration and entry of this Information Disclosure Statement and accompanying references under 37 CFR 1.97(d).

Please charge the processing fee under 1.17(p) of \$180.00 to Deposit Account 500417.

09/909,975

CERTIFICATION PARAGRAPH

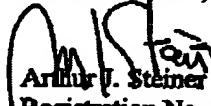
The undersigned certifies that, to the best of his knowledge, each item of information contained in this Information Disclosure Statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement as described in 37 CFR 1.97(e)(1).

Each non-English language reference was cited in a corresponding foreign application search report or office action and its relevance discussed therein. A copy of the foreign search report or office action, together with an English language version thereof, is attached for the Examiner's information.

Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

MCDERMOTT, WILL & EMERY



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Date: November 24, 2003

Applicant	Title (NAME)	Docket No.	57454-162
SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD OF THE SAME			
Title:		Serial/Reg. Patent No.	<u>09/908,975</u>
Date Sent:	11/24/2003	<input checked="" type="checkbox"/> Hand Certified	<input type="checkbox"/> Fax <input type="checkbox"/> E-mail <input type="checkbox"/> CIP
Other:	Tierenthaler Letter	<input type="checkbox"/> Dv. <input type="checkbox"/> RCE <input type="checkbox"/> RCE <input type="checkbox"/> RCE	<input type="checkbox"/> Cert. of Mailing <input type="checkbox"/> Express Mail No. _____
<input type="checkbox"/> pages of Specification <input type="checkbox"/> pages of Claims <input type="checkbox"/> pages of Abstract <input type="checkbox"/> pages of Formal/Informal Drawings <input type="checkbox"/> Small Entity <input type="checkbox"/> Large Entity <input type="checkbox"/> Declaration/Power of Attorney <input type="checkbox"/> Recognition of Assignment/Security Agreement <input type="checkbox"/> Information Disclosure Statement <input checked="" type="checkbox"/> 1 Form PTO 146 <input type="checkbox"/> 2 copies of cited references <input type="checkbox"/> Preliminary Amendment <input type="checkbox"/> Response to Missing Parts Notice <input type="checkbox"/> Reg. to Notice to Connect AIA Papers <input type="checkbox"/> Certified Copy of Priority Doc. <input type="checkbox"/> Claim for Continuation Priority <input type="checkbox"/> Response to Amendment to Office Action of _____ <input type="checkbox"/> Request for _____ Extension of Time.			
<input type="checkbox"/> Check for \$ <input type="checkbox"/> Charge Deposit Acct. 5004-173 <input type="checkbox"/> 160.00 <input type="checkbox"/> Attn. <input type="checkbox"/> A.S. <input type="checkbox"/> Tmt. # <input type="checkbox"/> 4236 <input type="checkbox"/> Secy. P.R. <input type="checkbox"/> MUS/TL/DR			
CAS Deposit: <u>10484.00</u>			
THE PATENT AND TRADEMARK OFFICE DATE STAMPED HEREON IS ACKNOWLEDGEMENT THAT THE ITEMS CHECKED ABOVE, WERE RECEIVED BY THE PTO ON THE DATE STAMPER.			



SHEET 1 OF 1

***EXAMINER:** Initial if references considered, whether or not citation is in conformance with MPEP 603. Draw line through citation if not in conformance and not considered.
Include copy of this form and dead communication to applicant.